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**Understanding Embedded - CPLDs (Complex Programmable Logic Devices)** 

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

# **Applications of Embedded - CPLDs**

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	5 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	2
Number of Macrocells	32
Number of Gates	600
Number of I/O	36
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7032stc44-5n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

- Additional design entry and simulation support provided by EDIF 2 0 0 and 3 0 0 netlist files, library of parameterized modules (LPM), Verilog HDL, VHDL, and other interfaces to popular EDA tools from manufacturers such as Cadence, Exemplar Logic, Mentor Graphics, OrCAD, Synopsys, and VeriBest
- Programming support
  - Altera's Master Programming Unit (MPU) and programming hardware from third-party manufacturers program all MAX 7000 devices
  - The BitBlaster<sup>TM</sup> serial download cable, ByteBlasterMV<sup>TM</sup> parallel port download cable, and MasterBlaster<sup>TM</sup> serial/universal serial bus (USB) download cable program MAX 7000S devices

# General Description

The MAX 7000 family of high-density, high-performance PLDs is based on Altera's second-generation MAX architecture. Fabricated with advanced CMOS technology, the EEPROM-based MAX 7000 family provides 600 to 5,000 usable gates, ISP, pin-to-pin delays as fast as 5 ns, and counter speeds of up to 175.4 MHz. MAX 7000S devices in the -5, -6, -7, and -10 speed grades as well as MAX 7000 and MAX 7000E devices in -5, -6, -7, -10P, and -12P speed grades comply with the PCI Special Interest Group (PCI SIG) *PCI Local Bus Specification, Revision 2.2.* See Table 3 for available speed grades.

Device					Speed	l Grade				
	-5	-6	-7	-10P	-10	-12P	-12	-15	-15T	-20
EPM7032		<b>✓</b>	<b>✓</b>		<b>✓</b>		<b>✓</b>	<b>✓</b>	<b>✓</b>	
EPM7032S	<b>✓</b>	<b>✓</b>	<b>✓</b>		<b>✓</b>					
EPM7064		<b>✓</b>	<b>✓</b>		~		<b>✓</b>	<b>✓</b>		
EPM7064S	<b>✓</b>	<b>✓</b>	<b>✓</b>		~					
EPM7096			<b>✓</b>		~		<b>✓</b>	<b>✓</b>		
EPM7128E			<b>✓</b>	<b>✓</b>	~		<b>✓</b>	<b>✓</b>		<b>✓</b>
EPM7128S		<b>✓</b>	<b>✓</b>		<b>✓</b>			<b>✓</b>		
EPM7160E				<b>✓</b>	<b>✓</b>		<b>✓</b>	<b>✓</b>		<b>✓</b>
EPM7160S		<b>✓</b>	<b>✓</b>		~			<b>✓</b>		
EPM7192E						<b>✓</b>	<b>✓</b>	<b>✓</b>		<b>✓</b>
EPM7192S			<b>✓</b>		<b>✓</b>			<b>✓</b>		
EPM7256E						<b>✓</b>	<b>✓</b>	<b>✓</b>		<b>✓</b>
EPM7256S			<b>✓</b>		<b>✓</b>			<b>✓</b>		

MAX 7000 devices contain from 32 to 256 macrocells that are combined into groups of 16 macrocells, called logic array blocks (LABs). Each macrocell has a programmable-AND/fixed-OR array and a configurable register with independently programmable clock, clock enable, clear, and preset functions. To build complex logic functions, each macrocell can be supplemented with both shareable expander product terms and high-speed parallel expander product terms to provide up to 32 product terms per macrocell.

The MAX 7000 family provides programmable speed/power optimization. Speed-critical portions of a design can run at high speed/full power, while the remaining portions run at reduced speed/low power. This speed/power optimization feature enables the designer to configure one or more macrocells to operate at 50% or lower power while adding only a nominal timing delay. MAX 7000E and MAX 7000S devices also provide an option that reduces the slew rate of the output buffers, minimizing noise transients when non-speed-critical signals are switching. The output drivers of all MAX 7000 devices (except 44-pin devices) can be set for either 3.3-V or 5.0-V operation, allowing MAX 7000 devices to be used in mixed-voltage systems.

The MAX 7000 family is supported by Altera development systems, which are integrated packages that offer schematic, text—including VHDL, Verilog HDL, and the Altera Hardware Description Language (AHDL)—and waveform design entry, compilation and logic synthesis, simulation and timing analysis, and device programming. The software provides EDIF 2 0 0 and 3 0 0, LPM, VHDL, Verilog HDL, and other interfaces for additional design entry and simulation support from other industry-standard PC- and UNIX-workstation-based EDA tools. The software runs on Windows-based PCs, as well as Sun SPARCstation, and HP 9000 Series 700/800 workstations.



For more information on development tools, see the MAX+PLUS II Programmable Logic Development System & Software Data Sheet and the Quartus Programmable Logic Development System & Software Data Sheet.

# Functional Description

The MAX 7000 architecture includes the following elements:

- Logic array blocks
- Macrocells
- Expander product terms (shareable and parallel)
- Programmable interconnect array
- I/O control blocks

The MAX 7000 architecture includes four dedicated inputs that can be used as general-purpose inputs or as high-speed, global control signals (clock, clear, and two output enable signals) for each macrocell and I/O pin. Figure 1 shows the architecture of EPM7032, EPM7064, and EPM7096 devices.

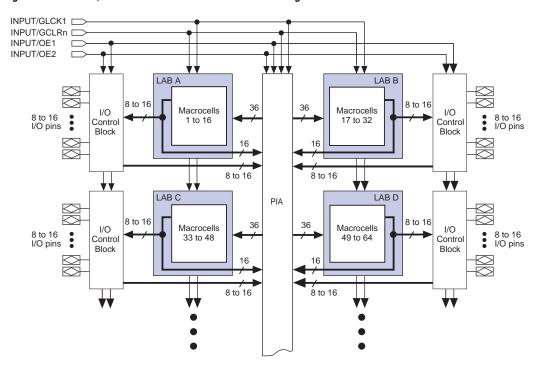


Figure 1. EPM7032, EPM7064 & EPM7096 Device Block Diagram



For more information on using the Jam language, refer to AN 122: Using Jam STAPL for ISP & ICR via an Embedded Processor.

The ISP circuitry in MAX 7000S devices is compatible with IEEE Std. 1532 specification. The IEEE Std. 1532 is a standard developed to allow concurrent ISP between multiple PLD vendors.

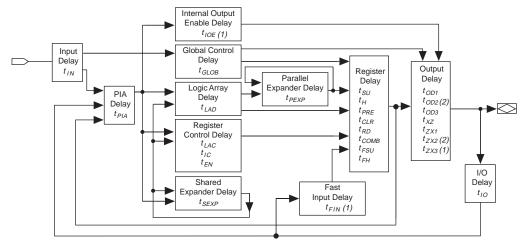
# **Programming Sequence**

During in-system programming, instructions, addresses, and data are shifted into the MAX 7000S device through the TDI input pin. Data is shifted out through the TDO output pin and compared against the expected data.

Programming a pattern into the device requires the following six ISP stages. A stand-alone verification of a programmed pattern involves only stages 1, 2, 5, and 6.

- Enter ISP. The enter ISP stage ensures that the I/O pins transition smoothly from user mode to ISP mode. The enter ISP stage requires 1 ms.
- 2. *Check ID*. Before any program or verify process, the silicon ID is checked. The time required to read this silicon ID is relatively small compared to the overall programming time.
- 3. *Bulk Erase*. Erasing the device in-system involves shifting in the instructions to erase the device and applying one erase pulse of 100 ms.
- Program. Programming the device in-system involves shifting in the address and data and then applying the programming pulse to program the EEPROM cells. This process is repeated for each EEPROM address.
- Verify. Verifying an Altera device in-system involves shifting in addresses, applying the read pulse to verify the EEPROM cells, and shifting out the data for comparison. This process is repeated for each EEPROM address.
- 6. Exit ISP. An exit ISP stage ensures that the I/O pins transition smoothly from ISP mode to user mode. The exit ISP stage requires 1 ms.

Figure 12. MAX 7000 Timing Model



#### Notes:

- (1) Only available in MAX 7000E and MAX 7000S devices.
- (2) Not available in 44-pin devices.

The timing characteristics of any signal path can be derived from the timing model and parameters of a particular device. External timing parameters, which represent pin-to-pin timing delays, can be calculated as the sum of internal parameters. Figure 13 shows the internal timing relationship of internal and external delay parameters.



For more infomration, see *Application Note* 94 (Understanding MAX 7000 *Timing*).

Tables 19 through 26 show the MAX 7000 and MAX 7000E AC operating conditions.

Symbol	Parameter	Conditions	-6 Speed Grade		-7 Spee	d Grade	Unit
			Min	Max	Min	Max	
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		6.0		7.5	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		6.0		7.5	ns
t <sub>SU</sub>	Global clock setup time		5.0		6.0		ns
t <sub>H</sub>	Global clock hold time		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input	(2)	2.5		3.0		ns
t <sub>FH</sub>	Global clock hold time of fast input	(2)	0.5		0.5		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		4.0		4.5	ns
t <sub>CH</sub>	Global clock high time		2.5		3.0		ns
t <sub>CL</sub>	Global clock low time		2.5		3.0		ns
t <sub>ASU</sub>	Array clock setup time		2.5		3.0		ns
t <sub>AH</sub>	Array clock hold time		2.0		2.0		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		6.5		7.5	ns
t <sub>ACH</sub>	Array clock high time		3.0		3.0		ns
t <sub>ACL</sub>	Array clock low time		3.0		3.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(3)	3.0		3.0		ns
t <sub>ODH</sub>	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		ns
t <sub>CNT</sub>	Minimum global clock period			6.6		8.0	ns
f <sub>CNT</sub>	Maximum internal global clock frequency	(5)	151.5		125.0		MHz
t <sub>ACNT</sub>	Minimum array clock period			6.6		8.0	ns
f <sub>ACNT</sub>	Maximum internal array clock frequency	(5)	151.5		125.0		MHz
f <sub>MAX</sub>	Maximum clock frequency	(6)	200		166.7		MHz

Table 24	4. MAX 7000 & MAX 7000E Int	ernal Timing Parame	eters Note	e (1)			
Symbol	Parameter	Conditions		Speed	Grade		Unit
			MAX 700	10E (-12P)		000 (-12) 00E (-12)	
			Min	Max	Min	Max	
t <sub>IN</sub>	Input pad and buffer delay			1.0		2.0	ns
t <sub>IO</sub>	I/O input pad and buffer delay			1.0		2.0	ns
t <sub>FIN</sub>	Fast input delay	(2)		1.0		1.0	ns
t <sub>SEXP</sub>	Shared expander delay			7.0		7.0	ns
t <sub>PEXP</sub>	Parallel expander delay			1.0		1.0	ns
t <sub>LAD</sub>	Logic array delay			7.0		5.0	ns
t <sub>LAC</sub>	Logic control array delay			5.0		5.0	ns
t <sub>IOE</sub>	Internal output enable delay	(2)		2.0		2.0	ns
t <sub>OD1</sub>	Output buffer and pad delay Slow slew rate = off V <sub>CCIO</sub> = 5.0 V	C1 = 35 pF		1.0		3.0	ns
t <sub>OD2</sub>	Output buffer and pad delay Slow slew rate = off V <sub>CCIO</sub> = 3.3 V	C1 = 35 pF (7)		2.0		4.0	ns
t <sub>OD3</sub>	Output buffer and pad delay Slow slew rate = on V <sub>CCIO</sub> = 5.0 V or 3.3 V	C1 = 35 pF (2)		5.0		7.0	ns
t <sub>ZX1</sub>	Output buffer enable delay Slow slew rate = off V <sub>CCIO</sub> = 5.0 V	C1 = 35 pF		6.0		6.0	ns
t <sub>ZX2</sub>	Output buffer enable delay Slow slew rate = off V <sub>CCIO</sub> = 3.3 V	C1 = 35 pF (7)		7.0		7.0	ns
t <sub>ZX3</sub>	Output buffer enable delay Slow slew rate = on V <sub>CCIO</sub> = 5.0 V or 3.3 V	C1 = 35 pF (2)		10.0		10.0	ns
$t_{XZ}$	Output buffer disable delay	C1 = 5 pF		6.0		6.0	ns
t <sub>SU</sub>	Register setup time		1.0		4.0		ns
t <sub>H</sub>	Register hold time		6.0		4.0		ns
t <sub>FSU</sub>	Register setup time of fast input	(2)	4.0		2.0		ns
t <sub>FH</sub>	Register hold time of fast input	(2)	0.0		2.0		ns
t <sub>RD</sub>	Register delay			2.0		1.0	ns
t <sub>COMB</sub>	Combinatorial delay			2.0		1.0	ns
t <sub>IC</sub>	Array clock delay			5.0		5.0	ns
t <sub>EN</sub>	Register enable time			7.0		5.0	ns
t <sub>GLOB</sub>	Global control delay			2.0		0.0	ns
t <sub>PRE</sub>	Register preset time			4.0		3.0	ns
t <sub>CLR</sub>	Register clear time			4.0		3.0	ns
t <sub>PIA</sub>	PIA delay			1.0		1.0	ns
t <sub>LPA</sub>	Low-power adder	(8)		12.0		12.0	ns

Table 2	5. MAX 7000 & MAX 7000E	External Timing I	Paramete	ers /	lote (1)				
Symbol	Parameter	Conditions			Speed	Grade			Unit
			-	15	-1	5T	-2	20	
			Min	Max	Min	Max	Min	Max	
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		15.0		15.0		20.0	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		15.0		15.0		20.0	ns
t <sub>SU</sub>	Global clock setup time		11.0		11.0		12.0		ns
t <sub>H</sub>	Global clock hold time		0.0		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input	(2)	3.0		-		5.0		ns
t <sub>FH</sub>	Global clock hold time of fast input	(2)	0.0		-		0.0		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		8.0		8.0		12.0	ns
t <sub>CH</sub>	Global clock high time		5.0		6.0		6.0		ns
t <sub>CL</sub>	Global clock low time		5.0		6.0		6.0		ns
t <sub>ASU</sub>	Array clock setup time		4.0		4.0		5.0		ns
t <sub>AH</sub>	Array clock hold time		4.0		4.0		5.0		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		15.0		15.0		20.0	ns
t <sub>ACH</sub>	Array clock high time		6.0		6.5		8.0		ns
t <sub>ACL</sub>	Array clock low time		6.0		6.5		8.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(3)	6.0		6.5		8.0		ns
t <sub>ODH</sub>	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		1.0		ns
t <sub>CNT</sub>	Minimum global clock period			13.0		13.0		16.0	ns
f <sub>CNT</sub>	Maximum internal global clock frequency	(5)	76.9		76.9		62.5		MHz
t <sub>ACNT</sub>	Minimum array clock period			13.0		13.0		16.0	ns
f <sub>ACNT</sub>	Maximum internal array clock frequency	(5)	76.9		76.9		62.5		MHz
f <sub>MAX</sub>	Maximum clock frequency	(6)	100		83.3	_	83.3	_	MHz

#### Notes to tables:

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This parameter applies to MAX 7000E devices only.
- This minimum pulse width for preset and clear applies for both global clear and array controls. The  $t_{LPA}$  parameter must be added to this minimum width if the clear or reset signal incorporates the  $t_{LAD}$  parameter into the signal path.
- (4) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (5) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (6) The  $f_{MAX}$  values represent the highest frequency for pipelined data.
- (7) Operating conditions:  $V_{CCIO} = 3.3 \text{ V} \pm 10\%$  for commercial and industrial use.
- (8) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{EN}$ ,  $t_{SEXP}$ ,  $t_{ACL}$ , and  $t_{CPPW}$  parameters for macrocells running in the low-power mode.

Tables 27 and 28 show the EPM7032S AC operating conditions.

Table 27. EPM7032S External Timing Parameters (Part 1 of 2)     Note (1)													
Symbol	Parameter	Conditions				Speed	Grade				Unit		
			-	-5 -(		6	-7		-10				
			Min	Max	Min	Max	Min	Max	Min	Max			
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns		
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns		
t <sub>SU</sub>	Global clock setup time		2.9		4.0		5.0		7.0		ns		
t <sub>H</sub>	Global clock hold time		0.0		0.0		0.0		0.0		ns		
t <sub>FSU</sub>	Global clock setup time of fast input		2.5		2.5		2.5		3.0		ns		
t <sub>FH</sub>	Global clock hold time of fast input		0.0		0.0		0.0		0.5		ns		
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		3.2		3.5		4.3		5.0	ns		
t <sub>CH</sub>	Global clock high time		2.0		2.5		3.0		4.0		ns		
t <sub>CL</sub>	Global clock low time		2.0		2.5		3.0		4.0		ns		
t <sub>ASU</sub>	Array clock setup time		0.7		0.9		1.1		2.0		ns		
t <sub>AH</sub>	Array clock hold time		1.8		2.1		2.7		3.0		ns		
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		5.4		6.6		8.2		10.0	ns		
t <sub>ACH</sub>	Array clock high time		2.5		2.5		3.0		4.0		ns		
t <sub>ACL</sub>	Array clock low time		2.5		2.5		3.0		4.0		ns		
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(2)	2.5		2.5		3.0		4.0		ns		
t <sub>ODH</sub>	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns		
t <sub>CNT</sub>	Minimum global clock period			5.7		7.0		8.6		10.0	ns		
f <sub>CNT</sub>	Maximum internal global clock frequency	(4)	175.4		142.9		116.3		100.0		MHz		
t <sub>ACNT</sub>	Minimum array clock period			5.7		7.0		8.6		10.0	ns		

Table 27. EPM7032S External Timing Parameters (Part 2 of 2) Note (1)											
Symbol	Parameter	Conditions				Speed	Grade	1			Unit
			-	5	-	6	-	7	-1	0	
			Min	Max	Min	Max	Min	Max	Min	Max	
f <sub>ACNT</sub>	Maximum internal array clock frequency	(4)	175.4		142.9		116.3		100.0		MHz
f <sub>MAX</sub>	Maximum clock frequency	(5)	250.0		200.0		166.7		125.0		MHz

Table 2	8. EPM7032\$ Internal Tim	ing Parameter	rs /	Note (1)							
Symbol	Parameter	Conditions				Speed	Grade	)			Unit
			_	5	-	6	-	7	-	10	
			Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>IN</sub>	Input pad and buffer delay			0.2		0.2		0.3		0.5	ns
t <sub>IO</sub>	I/O input pad and buffer delay			0.2		0.2		0.3		0.5	ns
t <sub>FIN</sub>	Fast input delay			2.2		2.1		2.5		1.0	ns
t <sub>SEXP</sub>	Shared expander delay			3.1		3.8		4.6		5.0	ns
t <sub>PEXP</sub>	Parallel expander delay			0.9		1.1		1.4		0.8	ns
$t_{LAD}$	Logic array delay			2.6		3.3		4.0		5.0	ns
t <sub>LAC</sub>	Logic control array delay			2.5		3.3		4.0		5.0	ns
t <sub>IOE</sub>	Internal output enable delay			0.7		0.8		1.0		2.0	ns
t <sub>OD1</sub>	Output buffer and pad delay	C1 = 35 pF		0.2		0.3		0.4		1.5	ns
t <sub>OD2</sub>	Output buffer and pad delay	C1 = 35 pF (6)		0.7		0.8		0.9		2.0	ns
t <sub>OD3</sub>	Output buffer and pad delay	C1 = 35 pF		5.2		5.3		5.4		5.5	ns
t <sub>ZX1</sub>	Output buffer enable delay	C1 = 35 pF		4.0		4.0		4.0		5.0	ns
t <sub>ZX2</sub>	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		4.5		5.5	ns
t <sub>ZX3</sub>	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		9.0	ns
$t_{XZ}$	Output buffer disable delay	C1 = 5 pF		4.0		4.0		4.0		5.0	ns
$t_{SU}$	Register setup time		0.8		1.0		1.3		2.0		ns
$t_H$	Register hold time		1.7		2.0		2.5		3.0		ns
t <sub>FSU</sub>	Register setup time of fast input		1.9		1.8		1.7		3.0		ns
t <sub>FH</sub>	Register hold time of fast input		0.6		0.7		0.8		0.5		ns
$t_{RD}$	Register delay			1.2		1.6		1.9		2.0	ns
$t_{COMB}$	Combinatorial delay			0.9		1.1		1.4		2.0	ns
t <sub>IC</sub>	Array clock delay			2.7		3.4		4.2		5.0	ns
t <sub>EN</sub>	Register enable time			2.6		3.3		4.0		5.0	ns
t <sub>GLOB</sub>	Global control delay			1.6		1.4		1.7		1.0	ns
t <sub>PRE</sub>	Register preset time			2.0		2.4		3.0		3.0	ns
t <sub>CLR</sub>	Register clear time			2.0		2.4		3.0		3.0	ns

Table 28. EPM7032S Internal Timing Parameters Note (1)												
Symbol	Parameter	Conditions				Speed	Grade				Unit	
			-	-5 -6 -7 -10								
			Min	Max	Min	Max	Min	Max	Min	Max		
t <sub>PIA</sub>	PIA delay	(7)		1.1		1.1		1.4		1.0	ns	
$t_{LPA}$	Low-power adder	(8)		12.0		10.0		10.0		11.0	ns	

#### Notes to tables:

- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t<sub>LPA</sub> parameter must be added to this minimum width if the clear or reset signal incorporates the t<sub>LAD</sub> parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The  $f_{MAX}$  values represent the highest frequency for pipelined data.
- (6) Operating conditions:  $V_{CCIO} = 3.3 \text{ V} \pm 10\%$  for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{EN}$ ,  $t_{SEXP}$ ,  $\mathbf{t_{ACL}}$ , and  $\mathbf{t_{CPPW}}$  parameters for macrocells running in the low-power mode.

Tables 29 and 30 show the EPM7064S AC operating conditions.

Table 29. EPM7064S External Timing Parameters (Part 1 of 2) Note (1)												
Symbol	Parameter	Conditions				Speed	Grade	)			Unit	
			-	5	-	6	-7		-10			
			Min	Max	Min	Max	Min	Max	Min	Max		
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns	
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns	
t <sub>SU</sub>	Global clock setup time		2.9		3.6		6.0		7.0		ns	
t <sub>H</sub>	Global clock hold time		0.0		0.0		0.0		0.0		ns	
t <sub>FSU</sub>	Global clock setup time of fast input		2.5		2.5		3.0		3.0		ns	
t <sub>FH</sub>	Global clock hold time of fast input		0.0		0.0		0.5		0.5		ns	
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		3.2		4.0		4.5		5.0	ns	
t <sub>CH</sub>	Global clock high time		2.0		2.5		3.0		4.0		ns	
t <sub>CL</sub>	Global clock low time		2.0		2.5		3.0		4.0		ns	
t <sub>ASU</sub>	Array clock setup time		0.7		0.9		3.0		2.0		ns	
t <sub>AH</sub>	Array clock hold time		1.8		2.1		2.0		3.0		ns	

Symbol	Parameter	Conditions	Speed Grade										
			-	5	-	6	-	7	-1	10	-		
			Min	Max	Min	Max	Min	Max	Min	Max			
t <sub>FSU</sub>	Register setup time of fast input		1.9		1.8		3.0		3.0		ns		
t <sub>FH</sub>	Register hold time of fast input		0.6		0.7		0.5		0.5		ns		
t <sub>RD</sub>	Register delay			1.2		1.6		1.0		2.0	ns		
t <sub>COMB</sub>	Combinatorial delay			0.9		1.0		1.0		2.0	ns		
t <sub>IC</sub>	Array clock delay			2.7		3.3		3.0		5.0	ns		
t <sub>EN</sub>	Register enable time			2.6		3.2		3.0		5.0	ns		
$t_{GLOB}$	Global control delay			1.6		1.9		1.0		1.0	ns		
$t_{PRE}$	Register preset time			2.0		2.4		2.0		3.0	ns		
t <sub>CLR</sub>	Register clear time			2.0		2.4		2.0		3.0	ns		
t <sub>PIA</sub>	PIA delay	(7)		1.1		1.3		1.0		1.0	ns		
$t_{LPA}$	Low-power adder	(8)		12.0		11.0		10.0		11.0	ns		

#### Notes to tables:

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t<sub>LPA</sub> parameter must be added to this minimum width if the clear or reset signal incorporates the t<sub>LAD</sub> parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The  $f_{MAX}$  values represent the highest frequency for pipelined data.
- (6) Operating conditions:  $V_{CCIO} = 3.3 \text{ V} \pm 10\%$  for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{EN}$ ,  $t_{SEXP}$ ,  $\mathbf{t_{ACL}}$ , and  $\mathbf{t_{CPPW}}$  parameters for macrocells running in the low-power mode.

Tables 31 and 32 show the EPM7128S AC operating conditions.

Table 3	11. EPM7128\$ External Time	ing Parameters	: No	te (1)							
Symbol	Parameter	Conditions				Speed	Grade	)			Unit
			-	6	-7		-1	-10		15	
			Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t <sub>SU</sub>	Global clock setup time		3.4		6.0		7.0		11.0		ns
t <sub>H</sub>	Global clock hold time		0.0		0.0		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns
t <sub>FH</sub>	Global clock hold time of fast input		0.0		0.5		0.5		0.0		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		4.0		4.5		5.0		8.0	ns
t <sub>CH</sub>	Global clock high time		3.0		3.0		4.0		5.0		ns
t <sub>CL</sub>	Global clock low time		3.0		3.0		4.0		5.0		ns
t <sub>ASU</sub>	Array clock setup time		0.9		3.0		2.0		4.0		ns
t <sub>AH</sub>	Array clock hold time		1.8		2.0		5.0		4.0		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		6.5		7.5		10.0		15.0	ns
t <sub>ACH</sub>	Array clock high time		3.0		3.0		4.0		6.0		ns
t <sub>ACL</sub>	Array clock low time		3.0		3.0		4.0		6.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(2)	3.0		3.0		4.0		6.0		ns
t <sub>ODH</sub>	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t <sub>CNT</sub>	Minimum global clock period			6.8		8.0		10.0		13.0	ns
f <sub>CNT</sub>	Maximum internal global clock frequency	(4)	147.1		125.0		100.0		76.9		MHz
t <sub>ACNT</sub>	Minimum array clock period			6.8		8.0		10.0		13.0	ns
f <sub>ACNT</sub>	Maximum internal array clock frequency	(4)	147.1		125.0		100.0		76.9		MHz
f <sub>MAX</sub>	Maximum clock frequency	(5)	166.7		166.7		125.0		100.0		MHz

Table 3	Table 36. EPM7192S Internal Timing Parameters (Part 2 of 2) Note (1)								
Symbol	Parameter	Conditions	Speed Grade						
			-7		-10		-15		
			Min	Max	Min	Max	Min	Max	1
t <sub>H</sub>	Register hold time		1.7		3.0		4.0		ns
t <sub>FSU</sub>	Register setup time of fast input		2.3		3.0		2.0		ns
t <sub>FH</sub>	Register hold time of fast input		0.7		0.5		1.0		ns
t <sub>RD</sub>	Register delay			1.4		2.0		1.0	ns
t <sub>COMB</sub>	Combinatorial delay			1.2		2.0		1.0	ns
$t_{IC}$	Array clock delay			3.2		5.0		6.0	ns
t <sub>EN</sub>	Register enable time			3.1		5.0		6.0	ns
$t_{GLOB}$	Global control delay			2.5		1.0		1.0	ns
t <sub>PRE</sub>	Register preset time			2.7		3.0		4.0	ns
t <sub>CLR</sub>	Register clear time			2.7		3.0		4.0	ns
t <sub>PIA</sub>	PIA delay	(7)		2.4		1.0		2.0	ns
$t_{LPA}$	Low-power adder	(8)		10.0		11.0		13.0	ns

#### Notes to tables:

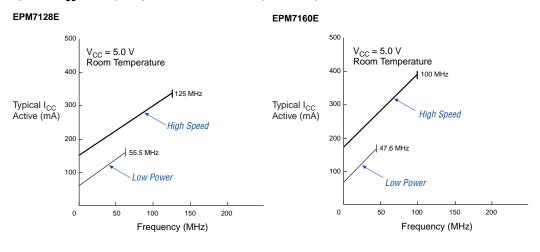
- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t<sub>LPA</sub> parameter must be added to this minimum width if the clear or reset signal incorporates the t<sub>LAD</sub> parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The  $f_{MAX}$  values represent the highest frequency for pipelined data.
- (6) Operating conditions:  $V_{CCIO} = 3.3 \text{ V} \pm 10\%$  for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{EN}$ ,  $t_{SEXP}$ ,  $\mathbf{t_{ACL}}$ , and  $\mathbf{t_{CPPW}}$  parameters for macrocells running in the low-power mode.

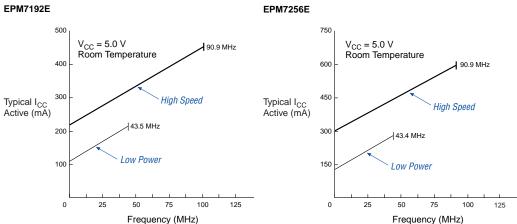
Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-15		
			Min	Max	Min	Max	Min	Max	
t <sub>IN</sub>	Input pad and buffer delay			0.3		0.5		2.0	ns
t <sub>IO</sub>	I/O input pad and buffer delay			0.3		0.5		2.0	ns
t <sub>FIN</sub>	Fast input delay			3.4		1.0		2.0	ns
t <sub>SEXP</sub>	Shared expander delay			3.9		5.0		8.0	ns
$t_{PEXP}$	Parallel expander delay			1.1		0.8		1.0	ns
$t_{LAD}$	Logic array delay			2.6		5.0		6.0	ns
t <sub>LAC</sub>	Logic control array delay			2.6		5.0		6.0	ns
t <sub>IOE</sub>	Internal output enable delay			0.8		2.0		3.0	ns
t <sub>OD1</sub>	Output buffer and pad delay	C1 = 35 pF		0.5		1.5		4.0	ns
t <sub>OD2</sub>	Output buffer and pad delay	C1 = 35 pF (6)		1.0		2.0		5.0	ns
t <sub>OD3</sub>	Output buffer and pad delay	C1 = 35 pF		5.5		5.5		8.0	ns
t <sub>ZX1</sub>	Output buffer enable delay	C1 = 35 pF		4.0		5.0		6.0	ns
t <sub>ZX2</sub>	Output buffer enable delay	C1 = 35 pF (6)		4.5		5.5		7.0	ns
t <sub>ZX3</sub>	Output buffer enable delay	C1 = 35 pF		9.0		9.0		10.0	ns
$t_{XZ}$	Output buffer disable delay	C1 = 5 pF		4.0		5.0		6.0	ns
t <sub>SU</sub>	Register setup time		1.1		2.0		4.0		ns
t <sub>H</sub>	Register hold time		1.6		3.0		4.0		ns
t <sub>FSU</sub>	Register setup time of fast input		2.4		3.0		2.0		ns
t <sub>FH</sub>	Register hold time of fast input		0.6		0.5		1.0		ns
$t_{RD}$	Register delay			1.1		2.0		1.0	ns
t <sub>COMB</sub>	Combinatorial delay			1.1		2.0		1.0	ns
t <sub>IC</sub>	Array clock delay			2.9		5.0		6.0	ns
$t_{EN}$	Register enable time			2.6		5.0		6.0	ns
t <sub>GLOB</sub>	Global control delay			2.8		1.0		1.0	ns
t <sub>PRE</sub>	Register preset time			2.7		3.0		4.0	ns
t <sub>CLR</sub>	Register clear time			2.7		3.0		4.0	ns
t <sub>PIA</sub>	PIA delay	(7)		3.0		1.0		2.0	ns
t <sub>LPA</sub>	Low-power adder	(8)		10.0	İ	11.0		13.0	ns

Table 39. MAX 7000 I <sub>CC</sub> Equation Constants							
Device	Α	В	С				
EPM7032	1.87	0.52	0.144				
EPM7064	1.63	0.74	0.144				
EPM7096	1.63	0.74	0.144				
EPM7128E	1.17	0.54	0.096				
EPM7160E	1.17	0.54	0.096				
EPM7192E	1.17	0.54	0.096				
EPM7256E	1.17	0.54	0.096				
EPM7032S	0.93	0.40	0.040				
EPM7064S	0.93	0.40	0.040				
EPM7128S	0.93	0.40	0.040				
EPM7160S	0.93	0.40	0.040				
EPM7192S	0.93	0.40	0.040				
EPM7256S	0.93	0.40	0.040				

This calculation provides an  $I_{CC}$  estimate based on typical conditions using a pattern of a 16-bit, loadable, enabled, up/down counter in each LAB with no output load. Actual  $I_{CC}$  values should be verified during operation because this measurement is sensitive to the actual pattern in the device and the environmental operating conditions.

Figure 14. I<sub>CC</sub> vs. Frequency for MAX 7000 Devices (Part 2 of 2)

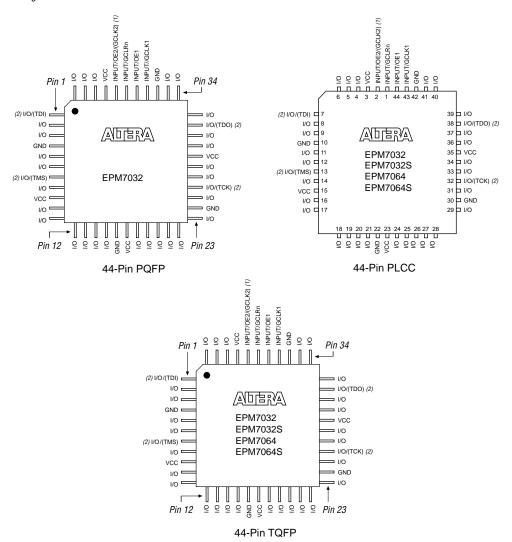




Figures 16 through 22 show the package pin-out diagrams for MAX 7000 devices.

Figure 16. 44-Pin Package Pin-Out Diagram

Package outlines not drawn to scale.



### Notes:

- (1) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (2) JTAG ports are available in MAX 7000S devices only.

# Revision History

The information contained in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.7 supersedes information published in previous versions. The following changes were made in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.7:

# Version 6.7

The following changes were made in the MAX 7000 Programmable Logic Device Family Data Sheet version 6.7:

Reference to AN 88: Using the Jam Language for ISP & ICR via an Embedded Processor has been replaced by AN 122: Using Jam STAPL for ISP & ICR via an Embedded Processor.

# Version 6.6

The following changes were made in the MAX 7000 Programmable Logic Device Family Data Sheet version 6.6:

- Added Tables 6 through 8.
- Added "Programming Sequence" section on page 17 and "Programming Times" section on page 18.

# Version 6.5

The following changes were made in the MAX 7000 Programmable Logic Device Family Data Sheet version 6.5:

Updated text on page 16.

## Version 6.4

The following changes were made in the MAX 7000 Programmable Logic Device Family Data Sheet version 6.4:

Added Note (5) on page 28.

## Version 6.3

The following changes were made in the MAX 7000 Programmable Logic Device Family Data Sheet version 6.3:

■ Updated the "Open-Drain Output Option (MAX 7000S Devices Only)" section on page 20.



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I.S. EN ISO 9001